LH5499

FEATURES

- Fast Access Times: 20/25/35/50/65/80 ns
- Full CMOS Dual Port Memory Array
- · Fully Asynchronous Read and Write
- Expandable in Width and Depth
- Full, Half-Full, and Empty Status Flags
- Read Retransmit Capability
- TTL Compatible I/O
- Packages:
 28-Pin, 600-mil DIP
 32-Pin PLCC
- Pin and Functionally Compatible with IDT7204

FUNCTIONAL DESCRIPTION

The LH5499 is a dual port memory with internal addressing to implement a First-In, First-Out algorithm. Through an advanced dual port architecture, it provides fully asynchronous read/write operation. Empty, Full, and Half-Full status flags are provided to prevent data overflow and underflow. Internal logic is provided for unlimited expansion in both word size and depth.

Read and Write operations automatically access sequential locations in memory in such a way that data is read out in the same order that it was written, that is on a First-In, First-Out basis. Since the address sequence is internally predefined, no external address information is required for the operation of this device. A ninth data bit is provided for parity or control information often needed in communication applications.

Empty, Full, and Half-Full status flags monitor the extent to which data has been written into the FIFO, and prevent improper operations (i.e., Read if the FIFO is empty, or Write if the FIFO is full). A retransmit feature resets the Read address pointer to its initial position, thereby allowing repetitive readout of the same data. Expansion in and Expansion out pins implement an expansion scheme that allows individual FIFOs to be cascaded to greater depth without incurring additional latency (bubblethrough) delays.

PIN CONNECTIONS

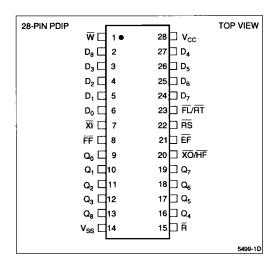


Figure 1. Pin Connections for PDIP Package

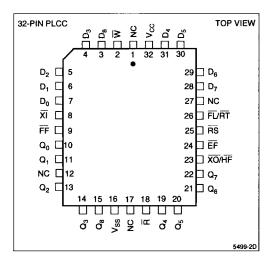


Figure 2. Pin Connections for PLCC Package

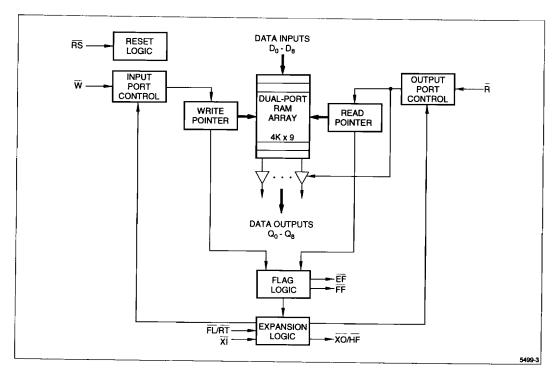


Figure 3. LH5499 Block Diagram

PIN DESCRIPTIONS

PIN	PIN TYPE *	DESCRIPTION
D ₀ – D ₈	1	Input Data Bus
Q ₀ – Q ₈	O/Z	Output Data Bus
W	1	Write Request
R	1	Read Request
EF	0	Empty Flag
FF	0	Full Flag

= Input, O = Output, Z = High-Impedance,	V = 1	Power Voltage Leve	1
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PIN	PIN TYPE *	DESCRIPTION
XO/HF	0	Expansion Out/Half-Full Flag
XI	1	Expansion In
FL/RT	I	First Load/Retransmit
RS	1	Reset
Vcc	V	Positive Power Supply
Vss	V	Ground

ABSOLUTE MAXIMUM RATINGS 1

PARAMETER	RATING					
Supply Voltage to Vss Potential	-0.5 V to 7 V					
Signal Pin Voltage to Vss Potential 3	-0.5 V to V _{CC} + 0.5 V (not to exceed 7 V)					
DC Output Current ²	± 50 mA					
Storage Temperature Range	-65°C to 150°C					
Power Dissipation (Package Limit)	1.0 W					
DC Voltage Applied to Outputs In High-Z State	-0.5 V to V _{CC} + 0.5 V (not to exceed 7 V)					

NOTES:

- Stresses greater than those listed under 'Absolute Maximum Ratings' may cause permanent damage to the device. This is a stress rating for transient conditions only. Functional operation of the device at these or any other conditions above those indicated in the 'Operating Range' of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- 2. Outputs should not be shorted for more than 30 seconds. No more than one output should be shorted at any time.
- 3. Negative undershoots of 1.5 V in amplitude are permitted for up to 10 ns once per cycle.

OPERATING RANGE

SYMBOL	SYMBOL PARAMETER		MAX	UNIT	
TA	Temperature, Ambient		70	°C	
Vcc Supply Voltage		4.5	5.5	٧	
Vss Supply Voltage		0	0	٧	
V _{IL} Logic '0' Input Voltage ¹		-0.5	0.8	٧	
V _{IH} Logic '1' Input Voltage		2.0	Vcc + 0.5	٧	

NOTE:

DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

SYMBOL	PARAMETER TEST CONDITIONS		MIN	MAX	UNIT
lu	Input Leakage Current	Vcc = 5.5 V, V _{IN} = 0 V to V _{CC}	-10	10	μΑ
llo	Output Leakage Current	R ≥ VIH, 0 V ≤ VOUT ≤ VCC	-10	10	μΑ
Vон	Output High Voltage	I _{OH} = -2.0 mA	2.4		٧
VoL	Output Low Voltage	I _{OL} = 8.0 mA		0.4	٧
lcc	Average Supply Current 1	Measured at f = 33 MHz		110	mA
ICC2	Average Standby Current 1	All Inputs = VIH		15	mA
Іссз	Power Down Current ¹	All inputs = V _{CC} - 0.2 V		8	mA

NOTE:

^{1.} Negative undershoots of 1.5 V in amplitude are permitted for up to 10 ns once per cycle.

^{1.} Icc, Icc2, and Icc3 are dependent upon actual output loading and cycle rates. Specified values are with outputs open.

AC TEST CONDITIONS

PARAMETER	RATING				
Input Pulse Levels	V _{SS} to 3 V				
Input Rise and Fall Times (10% to 90%)	5 ns				
Input Timing Reference Levels	1.5 V				
Output Reference Levels	1.5 V				
Output Load, Timing Tests	Figure 4				

CAPACITANCE 1,2

PARAMETER	RATING
C _{IN} (Input Capacitance)	5 pF
Cout (Output Capacitance)	7 pF

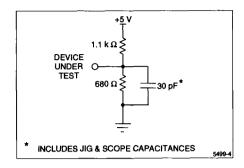


Figure 4. Output Load Circuit

NOTES:

- 1. Sample tested only.
- 2. Capacitances are maximum values at 25° C measured at 1.0 MHz with $V_{IN} = 0$ V.

AC ELECTRICAL CHARACTERISTICS ¹ (Over Operating Range)

SYMBOL	PARAMETER		t _A = 20 ns		t _A = 25 ns		t _A = 35 ns		t _A = 50 ns		t _A = 65 ns		80 ns	
SIMBUL			MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	UNITS
READ CYCLE TIMING														
tRC	Read Cycle Time	30	_	35	_	45	Ι_	65	Ι_	80	I _	100	_	ns
tA	Access Time	_	20	_	25	-	35	-	50	-	65	_	80	ns
ter	Read Recover Time	10	_	10	_	10	_	15	_	15	-	15	<u></u>	ns
tRPW	Read Pulse Width 2	20	-	25	_	35	-	50	_	65	_	80	-	ns
t _{RLZ}	Data Bus Active from Read LOW 3	5	† -	5	_	5	_	5	<u> </u>	5	_	10	 	ns
tw.z	Data Bus Active from Write HIGH 3,4	10	 	10	-	10	-	10	-	10	_	20	 _	ns
tov	Data Valid from Read Pulse HIGH	5	-	5	-	5	_	5	_	5	-	5	–	ns
tRHZ	Data Bus High-Z from Read HIGH 3	_	15	_	15	_	15	_	20	-	30	Ť.	30	ns
		w	RITE	CYCL	E TIM	ING						L		
two	Write Cycle Time	30	_ ·	35	_	45		65	_	80	Γ-	100	_	ns
twpw	Write Pulse Width 2	20	=	25	_	35	_	50	_	65	_	80	_	ns
twn	Write Recovery Time	10	T =	10	_	10	_	15	_	15	_	15	 _	ns
tos	Data Setup Time	10		10	_	15		20	_	20	_	20	_	ns
tрн	Data Hold Time	0		0	-	0		0	_	5	_	5	-	ns
RESET TIMING											- 1.0			
trsc	Reset Cycle Time	30	_	35	_	45	_	65	_	80	_	100	I _ I	ns
trs	Reset Pulse Width 2	20	-	25	_	35	_	50	_	65	_	80	_	ns
trsr	Reset Recovery Time	10	_	10		10	_	15	_	15	_	15	_	ns
trass	Read HIGH to RS HIGH	20	_	25	_	35	_	50		65		80	-	ns
twass	Write HIGH to RS HIGH	20	<u> </u>	25	_	35		50	_	65	_	80	_	ns
		RE	TRAN	SMIT	TIMI	NG ⁵					·			
terro	Retransmit Cycle Time	30	_	35	_	45	_	65		80		100	_	ns
terr	Retransmit Pulse Width 2	20	_	25		35	_	50		65		80		ns
tere	Retransmit Recovery Time	10	_	10	_	10	_	15	_	15		15		ns
			FL/	AG TIM										
terL	Reset LOW to Empty Flag LOW	_	30	_	35	_	45		65	_	80	_	100	ns
theh,eeh	Reset LOW to Half-Full and Full Flags HIGH	-	30	-	35	_	45	-	65	-	80	_	100	ns
tREF	Read LOW to Empty Flag LOW	_	25	_	25		35	_	45	_	60		60	ns
tref	Read HIGH to Full Flag HIGH	_	25		25		35	_	45	_	60	_	60	ns
twer	Write HIGH to Empty Flag HIGH		25	_	25	_	35	_	45	_	60	_	60	ns
twrr	Write LOW to Full Flag LOW	_	25	_	25		35	_	45	_	60	_	60	ns
twhF	Write LOW to Half-Full Flag LOW	_	30	_	35		45	_	65	_	80	-	100	ns
tahe	Read HIGH to Half-Full Flag HIGH	_	30	-1	35		45	_	65	_	80	_	100	ns
EXPANSION TIMING														
txoL	Expansion Out LOW	_	20	- 1	25	- 1	35	_	50	_	65	_ 1	80	ns
tхон	Expansion Out HIGH		20	_	25		35		50		65		80	ns
txı	Expansion In Pulse Width	20	_	25		35	-	50	_	65	-	80		ns
txiR	Expansion In Recovery Time	10	_	10	_	10		10	_	10		10		ns
txis	Expansion in Setup Time	10		10	_	15		15	-	15		15		ns

NOTES:

- 1. All timing measurements performed at 'AC Test Condition' levels.
- 2. Pulse widths less than minimum value are not allowed.
- 3. Values guaranteed by design not currently tested.
- 4. Only applies to read data flow-through mode.
- 5. See also Note 3, Figure 13.

OPERATIONAL DESCRIPTION

Reset

The device is reset whenever the Reset pin (\overline{RS}) is taken to a LOW state. The reset operation initializes both the read and write address pointers to the first memory location. The \overline{XI} and \overline{FL} pins are also sampled at this time to determine whether the device is in Single mode or Depth Expansion mode. A reset pulse is required when the device is first powered up. The Read (\overline{R}) and Write (\overline{W}) pins may be in any state when reset is initiated, but must be brought to a HIGH state \overline{LRPW} and \overline{LRPW} before the rising edge of \overline{RS} .

Write

A write cycle is initiated on the falling edge of the Write (\overline{W}) pin. Data setup and hold times must be observed on the data in (D_0-D_8) pins. A write operation is only possible if the FIFO is not full, (i.e. the Full flag pin is HIGH). Writes may occur independently of any ongoing read operations.

At the falling edge of the first write after the memory is half filled, the Half-Full flag will be asserted (\overline{HF} = LOW) and will remain asserted until the difference between the write pointer and read pointer indicates that the remaining data in the device is less than or equal to one half the total capacity of the FIFO. The Half-Full flag is deasserted (\overline{HF} = HIGH) by the appropriate rising edge of \overline{R} .

The Full flag is asserted (\overline{FF} = LOW) at the falling edge of the write operation which fills the last available location in the FIFO memory array. The Full flag will inhibit further writes until cleared by a valid read. The Full flag is deasserted (\overline{FF} = HIGH) after the next rising edge of \overline{R} releases another memory location.

Read

A read cycle is initiated on the falling edge of the Read (\overline{R}) pin. Read data becomes valid on the data out (Q_0-Q_0) pins after a time to from the falling edge of \overline{R} . After \overline{R} goes HIGH, the data out pins return to a high-impedance state. Reads may occur independent of any ongoing write operations. A read is only possible if the FIFO is not empty $(\overline{EF} = \text{HIGH})$.

Data Flow-Through

Read flow-through mode occurs when the Read (\overline{R}) pin is brought LOW while the FIFO is empty, and held LOW in anticipation of a write cycle. At the end of the next write cycle, the Empty flag will be momentarily de-asserted, and the data just written will become available on the data out pins after a maximum time of tweff + talenditional writes may occur while the \overline{R} pin remains LOW, but only data from the first write flows through to the outputs. Additional data, if any, can only be accessed by toggling \overline{R} .

Write flow-through mode occurs when the Write (\overline{W}) pin is brought LOW while the FIFO is full, and held LOW in anticipation of a read cycle. At the end of the read cycle, the Full flag will be momentarily deasserted, but then immediately reasserted in response to \overline{W} held LOW. Data is written into the FIFO on the rising edge of \overline{W} which may occur the the two after the read.

Retransmit

The FIFO can be made to reread previously read data through the retransmit function. Retransmit is initiated by pulsing $\overline{\text{RT}}$ LOW. This resets the internal read address pointer to the first physical location in the memory while leaving the internal write address pointer unchanged. Data between the read and write pointers may be reaccessed by subsequent reads. Both $\overline{\text{R}}$ and $\overline{\text{W}}$ must be inactive (HIGH) during the retransmit pulse. Retransmit is useful if no more than 4096 writes are performed between resets. Retransmit may affect the status of $\overline{\text{EF}}$, $\overline{\text{HF}}$, and $\overline{\text{FF}}$ flags, depending on the relocation of the read mode.

TIMING DIAGRAMS

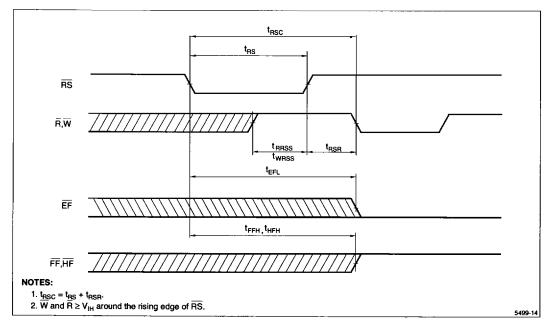


Figure 5. Reset Timing

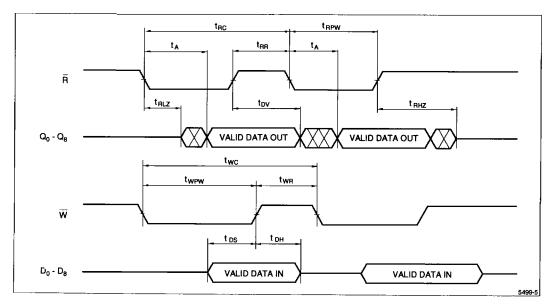


Figure 6. Asynchronous Write and Read Operation

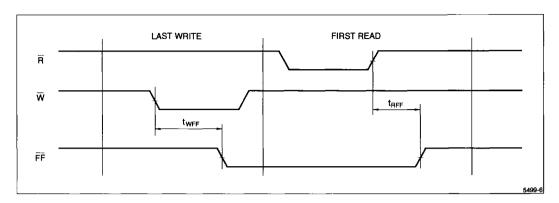


Figure 7. Full Flag from Last Write to First Read

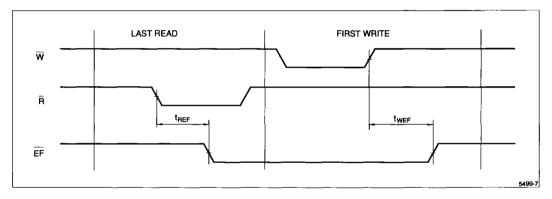


Figure 8. Empty Flag from Last Read to First Write

CMOS 4K × 9 FIFO LH5499

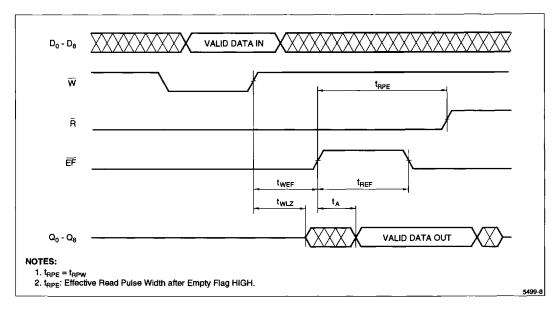


Figure 9. Read Data Flow-Through

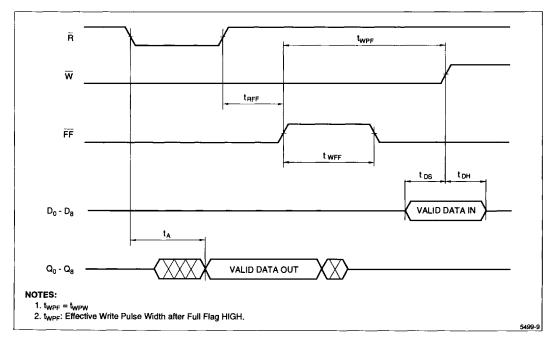


Figure 10. Write Data Flow-Through

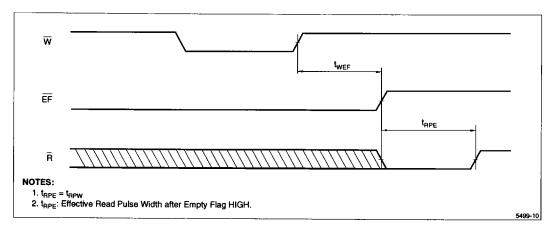


Figure 11. Empty Flag Timing

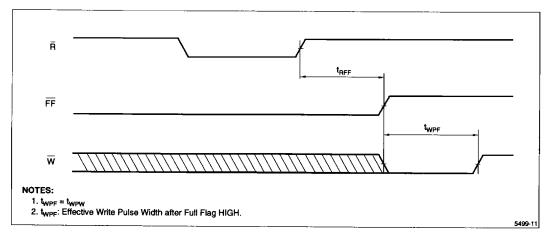


Figure 12. Full Flag Timing

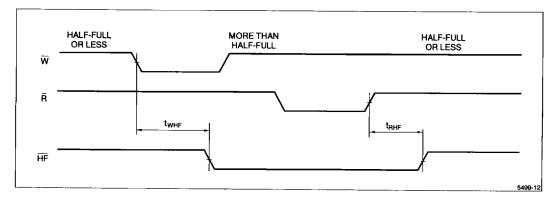


Figure 13. Half-Full Flag Timing

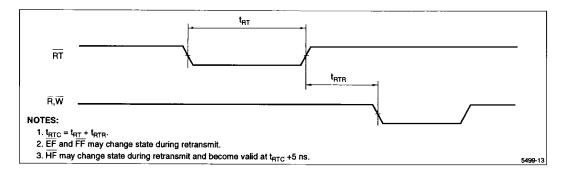


Figure 14. Retransmit Timing

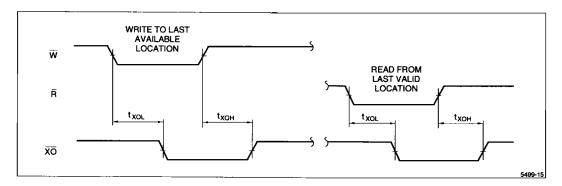


Figure 15. Expansion Out Timing

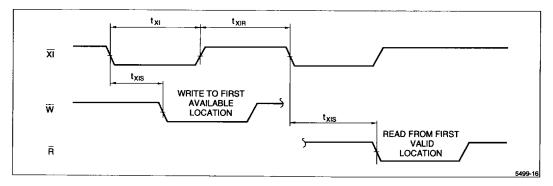


Figure 16. Expansion In Timing

OPERATIONAL MODES

Single Device Configuration

When depth expansion is not required for the given application, the device is placed in Single mode by tying the Expansion In pin (\overline{XI}) to ground. This pin is internally sampled during reset.

Width Expansion

Word-width expansion is implemented by placing multiple LH5499 devices in parallel. Each LH5499 should be configured for standalone mode. In this arrangement, the behavior of the status flags is identical for all devices; so, in principle, a representative value for each of these flags could be derived from any one device. In practice, it is better to derive 'composite' flag values using external logic, since there may be minor speed variations between different actual devices. (See Figures 17 and 18.)

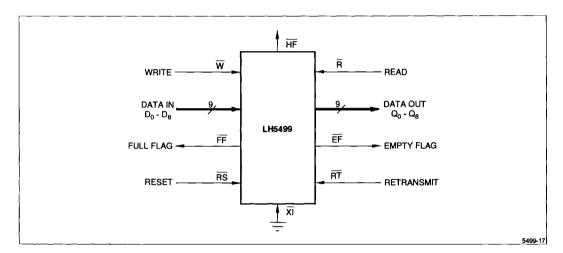


Figure 17. Single FIFO $(4K \times 9)$

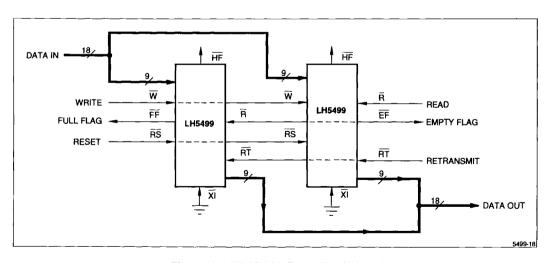


Figure 18. FIFO Width Expansion (4K × 18)

OPERATIONAL MODES (cont'd)

Depth Expansion

Depth expansion is implemented by configuring the required number of FIFOs in Expansion mode. In this arrangement, the FIFOs are connected in a circular fashion with the Expansion Out pin (\overline{XO}) of each device tied to the Expansion In pin (\overline{XI}) of the next device. One FIFO in this group must be designated as the first load device. This is accomplished by tying the First Load pin (\overline{FL}) of this device to ground. All other devices must have their \overline{FL} pin tied to a high level. In this mode, \overline{W} and \overline{R} signals

are shared by all devices, while internal logic controls the steering of data. Only one FIFO will be enabled for any given read cycle, so the common Data Out pins of all devices are wire-ORed together. Likewise, the common Data In pins of all devices are tied together.

In Expansion mode, external logic is required to generate a composite Full or Empty flag. This is achieved by ORing the FF pins of all devices and ORing the EF pins of all devices respectively. The Half-Full flag and Retransmit functions are not available in Depth Expansion mode.

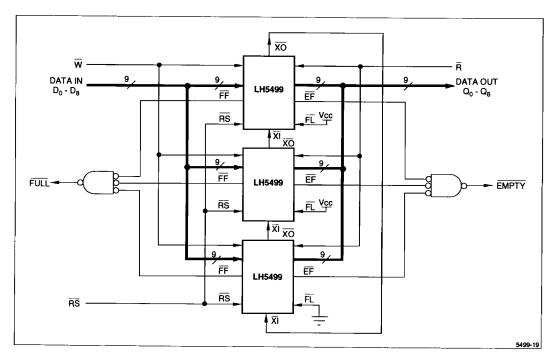


Figure 19. FIFO Depth Expansion (12288 × 9)

OPERATIONAL MODES (cont'd)

Compound Expansion

A combination of width and depth expansion can be easily implemented by operating groups of depth expanded FIFOs in parallel.

Bidirectional Operation

Applications which require bidirectional data buffering between two systems can be realized by operating LH5499 devices in parallel but opposite directions. The Data In pins of a device may be tied to the corresponding Data Out pins of another device operating in the opposite direction to form a single bidirectional bus interface. Care must be taken to assure that the appropriate read, write and flag signals are routed to each system. Both depth and width expansion may be used in this configuration.

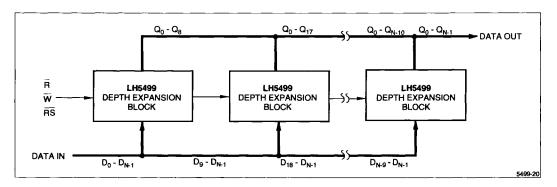


Figure 20. Compound FIFO

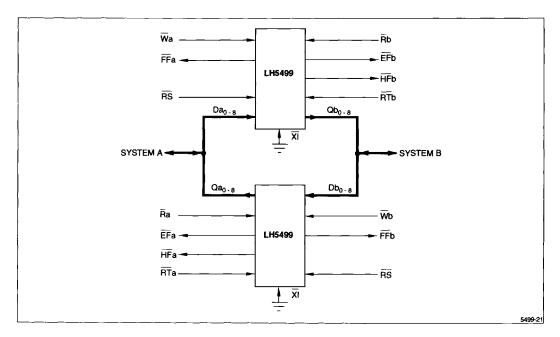
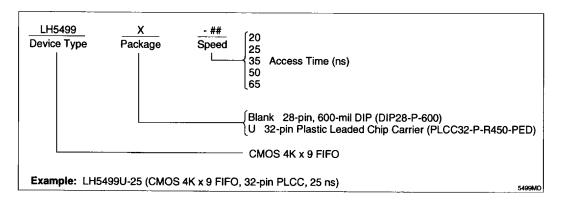


Figure 21. Bidirectional FIFO

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ORDERING INFORMATION



SHARP